Epoxy Resin 5050AB

I. Statement of purpose

Epoxy Resin **5050AB** is a **black** epoxy resin **potting compound** cured at room temperature and low temperature, with good fluidity, natural defoaming, room temperature curing or temperature curing. It is specially used for **machine potting** **electronic components potting, power supply encapsulation**, mold potting and other electronic parts insulation, moistureproof potting, confidentiality masking, and so on.

II. Pre-sclerotic properties.

	A glue 5050A	curing agent 5050B
Color:	Black	reddish-black
weight:	1.65	0.96
Viscosity 25℃:	**1500-4000CPS**	**500-2000CPS**

III. Conditions of use

1)mixing ratio:	**A：B=100：20（weight ratio）**
2)hardening condition:	**25℃×8H-10H or 55℃×2H(2g)**
3)usable time:	**25℃×45min（100g）**

IV. Methods of use.

1. Working environment: keep the glue container clean, A, B components strictly according to the weight ratio, accurate weighing, clockwise along the inner wall of the container to mix well and stand for 3-5 minutes after use.
2. Depending on the operating time and dosage of the glue, to avoid waste. When the temperature is lower than 15 ℃, please preheat the A glue to 30 ℃ before glue mixing, easy to operate (low temperature A glue will become thicker); after use must be sealed barrel lid, to avoid moisture absorption caused by the product scrap.
3. When the relative humidity is greater than 85%, the surface of the cured material is easy to absorb water in the air, forming a layer of white mist, so when the relative humidity is greater than 85%, it is not suitable for room temperature curing, it is recommended to use the heating curing.

V. Properties after hardening

1)hardness:	**shore D**	**<82**
2)withstand voltage:	**KV/mm**	**22**
3)bending strength:	**Kg/mm2**	**23**
4)volume resistance:	**Ohm3**	**1x10*15**
5)surface resistance:	**Ohmm2**	**5X10*15**
6）thermal conductivity：	**W/M.K**	**0.60**
7）electrostatic losses：	**1KHZ**	**0.42**
8）heat distortion temperature：	**℃**	**140**
9）water absorption：	**%**	**<0.15**
10)compressive strength：	**Kg/mm2**	**11.3**

The above performance data are typical data measured in a laboratory environment with a temperature of 25℃ and a humidity of 70%, and are for customers' reference only.